



JPCA

IEC/PAS 61189-3-913

Edition 1.0 2011-01

PUBLICLY AVAILABLE SPECIFICATION

PRE-STANDARD

**Test methods for electrical materials, printed boards and other interconnection structures and assemblies –
Part 3-913: Test methods for interconnection structures (printed boards) –
Electronic circuit board for high-brightness LEDs**

IEC/PAS 61189-3-913 Ed. 1.0 - Preview only Copy via ILNAS e-Shop

IEC/PAS 61189-3-913:2011(E)





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INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

PRICE CODE



ICS 31.180

ISBN 978-2-88912-343-8

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 3-913: Test methods for interconnection structures (printed boards) –
Electronic circuit board for high-brightness LEDs**

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IEC-PAS 61189-3-913 was submitted by the JPCA (Japan Electronics Packaging and Circuits Association) and has been processed by IEC technical committee 91: Electronics assembly technology.

It is based on JPCA-TMC-LED02T-2010. It is published as a double-logo IEC/ JPCA PAS.

The text of this PAS is based on the following document:

This PAS was approved for publication by the P-members of the committee concerned as indicated in the following document

Draft PAS	Report on voting
91/928/PAS	91/943A/RVD

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